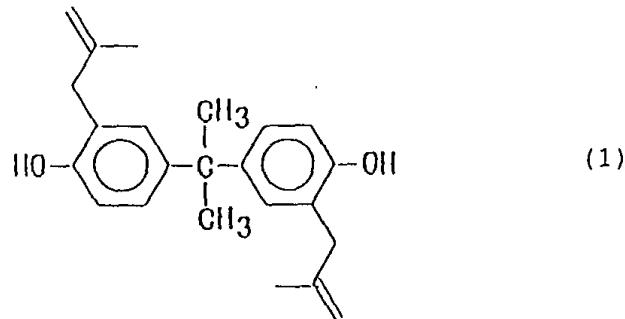


ABSTRACT

A thermosetting low-dielectric resin composition which has a low dielectric constant and a low dielectric tangent for use in a printed circuit board and which has excellent adhesion to a metal and scatters almost no resin when used for forming a prepeg by punching or cutting, the composition comprising a component (a): siloxane-modified polyimide, component (b): a compound containing 2 methylallyl groups and having the following formula (1) or a compound containing 3 allyl groups or 3 methylallyl groups and having the following formula (1A), and component (c): a compound containing at least 2 maleimide groups.

Formula (1):

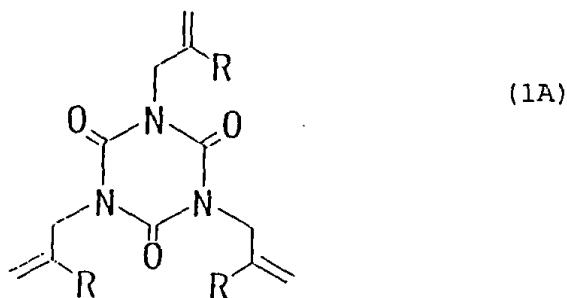
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Formula (1A):

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wherein R is a hydrogen atom or methyl group.